

ABSTRACT OF THE DISCLOSURE

5 A stacked package of semiconductor packaging units includes a direct electrical connection between leads of an upper semiconductor package unit, and includes direct electrical connections between selected leads of the upper semiconductor package unit and a lower semiconductor package unit. Leads of the upper semiconductor package unit are straightened, and chip-select and clock-enable leads are shortened and electrically connected to adjacent not-connected leads. Selected leads of the upper semiconductor package unit are electrically connected directly to underlying leads of the lower semiconductor packaging unit. Electrical connections preferably are solder connections.

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